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## FL77904

# Phase-cut Dimmable Compact LED Direct AC Driver

### Features

- The simplest Direct AC LED Driver with Only Two External RC Passive Components
- Wide AC Input Range: 90~305 V<sub>AC</sub>
- Four Integrated High-Voltage LED Constant Current Sinks of up to 75 mA RMS Input Current Capability
- High Power Factor (above 0.98 in normal configuration) Low Harmonic Content (THD under 20% in normal configuration)
- Low Flicker Index by Self Valley Fill with No Degradation of PF and THD
- Adjustable LED Power with an External Current Sense Resistor
- TRIAC Dimmable (Leading/Trailing Edge)
- Rheostat Dimmable Flexible LED Forward Voltage Configuration
- Power Scalability with Multiple Driver ICs
- Over-Temperature Protection (OTP)
- Compact SOIC 8-Lead Package

### Description

The FL77904 is a direct AC line LED driver with a minimal number of external RC passive components. In normal configuration, one resistor adjusts LED current for desired system luminance and another bypass capacitor provides a stable voltage to an internal biasing shunt regulator.

The FL77904 provides phase-cut dimming with wide dimming range, smooth dimming control and good dimmer compatibility. Optimized levels of each LED strings' current regulation achieve over 0.98 high PF and less than 20% low THD which makes the FL77904 suitable for high-efficiency LED lighting systems. The FL77904 can be also used with a simple rheostat dimmer switches which are suitable for desktop or indoor lamps.

Flicker index is significantly improved by using proprietary self valley fill technique without degrading PF and THD. The cost effective solution brings low line ripple light quality with system compactness.

Operation of FL77904 admits driving higher-wattage systems, such as street lights and down lights, by simply parallel connecting the driver ICs.

### Applications

- General LED Driving Solution for Residential, Commercial and Industrial Lighting

### Ordering Information

| Part Number | Operating Temperature Range | Package                                                                                   | Packing Method |
|-------------|-----------------------------|-------------------------------------------------------------------------------------------|----------------|
| FL77904MX   | -40 to 125°C                | 8-Lead, Small Outline Integrated Circuit (SOIC) JEDEC MS012 150" Narrow Body, Exposed Pad | 2,500 per Reel |

## Typical Application

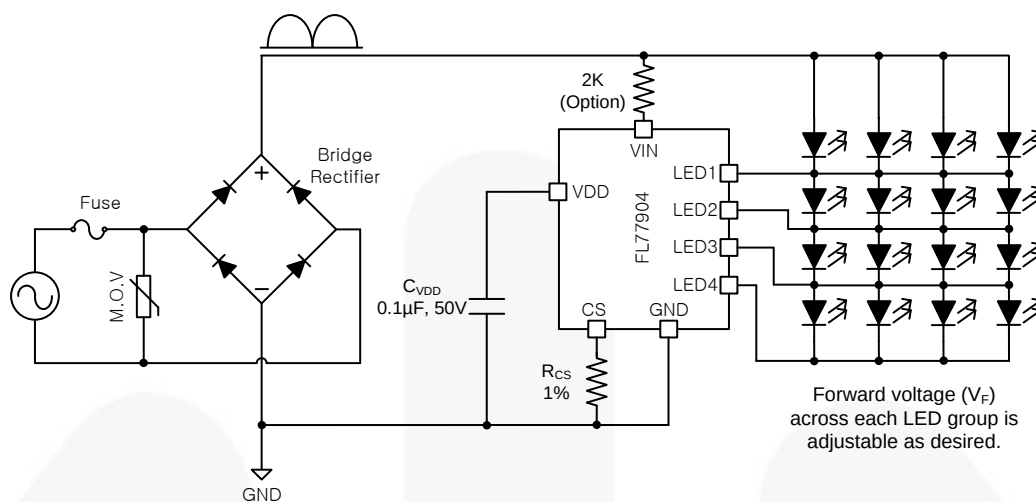


Figure 1. Typical Application Schematic

## Block Diagram

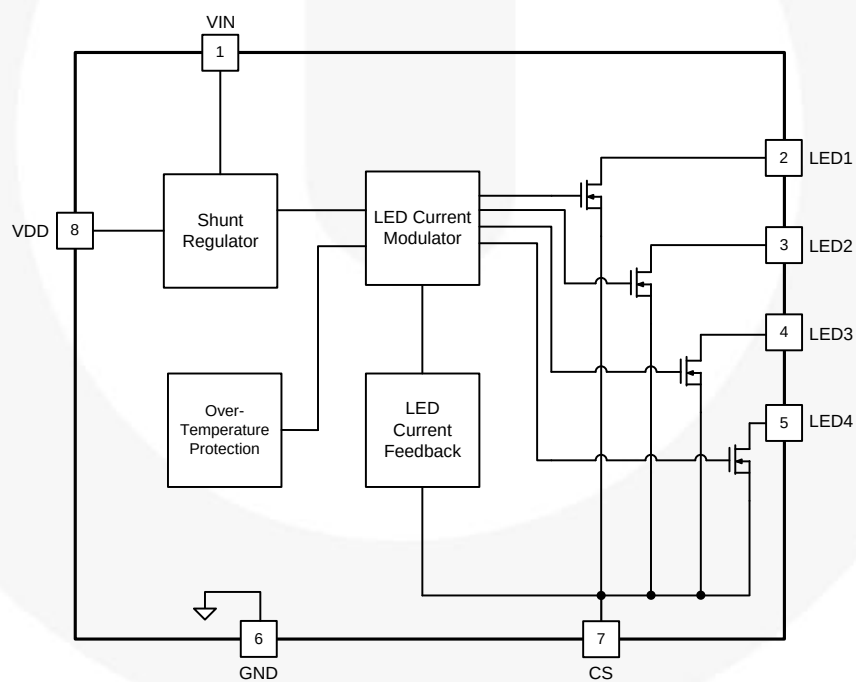


Figure 2. Simplified FL77904 Block Diagram

## Pin Configuration

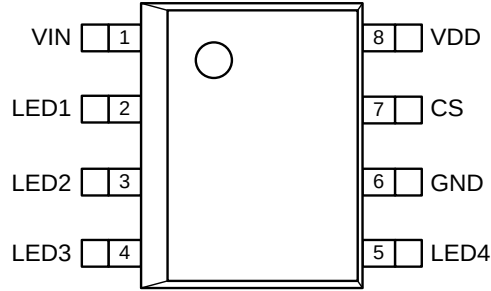


Figure 3. Pin Configuration (Top View)

## Thermal Characteristics <sup>(1) (2)</sup>

| Component | Package                                                                                      | $\theta_{JA}$<br>(1S PCB) | $\theta_{JA}$<br>(2S2P PCB) | Units |
|-----------|----------------------------------------------------------------------------------------------|---------------------------|-----------------------------|-------|
| FL77904MX | 8-Lead, Small Outline Integrated Circuit (SOIC)<br>JEDEC MS012 150" Narrow Body, Exposed Pad | 156                       | 37                          | °C/W  |

### Notes:

1.  $\theta_{JA}$ : Thermal resistance between junction and ambient, dependent on the PCB design, heat sinking, and airflow. The value given is for natural convection with no heatsink using the 1S and 2S2P boards, as specified in JEDEC standards JESD51-2, JESD51-5, and JESD51-7, as appropriate.
2. Junction-to-ambient thermal resistance is highly dependent on application and PCB layout. In application where the device dissipates high levels of power during operation, special care of thermal dissipation issues in PCB design must be taken.

## Pin Definitions

| Pin# | Name | Description                                                                                                                                                                                                                             |
|------|------|-----------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|
| 1    | VIN  | <b>Rectified AC Input Voltage.</b> Connect this pin to rectified AC voltage after a bridge rectifier.                                                                                                                                   |
| 2    | LED1 | <b>LED String Cathodes.</b> Connect cathode(s) of each LED group to these pins.                                                                                                                                                         |
| 3    | LED2 |                                                                                                                                                                                                                                         |
| 4    | LED3 |                                                                                                                                                                                                                                         |
| 5    | LED4 |                                                                                                                                                                                                                                         |
| 6    | GND  | <b>Ground Reference Pin.</b> Tie this pin directly to local ground plane. This ground should not be tied to earth ground because it is not isolated from AC mains.                                                                      |
| 7    | CS   | <b>LED Current Sense.</b> Limits the LED current depending on voltage across sensing resistor. The CS pin is used to set the LED current regulation target.                                                                             |
| 8    | VDD  | <b>Internal Biasing Shunt Regulator Output.</b> This pin supplies current to internal circuitry. A 17-V shunt regulator is internally connected to this pin. A bypassing capacitor is recommended to be added to reduce noise from VIN. |
| 0    | EP   | <b>Exposed Thermal Pad.</b> EP is not tied to GND inside the IC. It is recommended to tie it to GND externally.                                                                                                                         |

## Absolute Maximum Ratings

Stresses exceeding the absolute maximum ratings may damage the device. The device may not function or be operable above the recommended operating conditions and stressing the parts to these levels is not recommended. In addition, extended exposure to stresses above the recommended operating conditions may affect device reliability. The absolute maximum ratings are stress ratings only.

| Symbol     | Parameter            | Min. | Max. | Unit |
|------------|----------------------|------|------|------|
| $V_{IN}$   | VIN Voltage          | -0.3 | 500  | V    |
| $V_{LED1}$ | LED1 Pin Voltage     | -0.3 | 500  | V    |
| $V_{LED2}$ | LED2 Pin Voltage     | -0.3 | 500  | V    |
| $V_{LED3}$ | LED3 Pin Voltage     | -0.3 | 500  | V    |
| $V_{LED4}$ | LED4 Pin Voltage     | -0.3 | 200  | V    |
| $V_{CS}$   | CS Pin Voltage       | -0.3 | 6    | V    |
| $T_J$      | Junction Temperature | -55  | +150 | °C   |
| $T_{STG}$  | Storage Temperature  | -65  | +150 | °C   |
| $I_{LED1}$ | LED1 Current         |      | 60   | mA   |
| $I_{LED2}$ | LED2 Current         |      | 80   | mA   |
| $I_{LED3}$ | LED3 Current         |      | 100  | mA   |
| $I_{LED4}$ | LED4 Current         |      | 150  | mA   |

### Notes:

- Stress beyond those listed under Absolute Maximum Ratings may cause permanent damage to the device.
- All voltage values, except differential voltages, are given with respect to the GND pin.
- Human Body Model, ANSI/ESDA/JEDEC JS-001-2012: 0.8 kV at Pins 1~4, 0.4 kV at Pin 5, 1.5 kV at Pins 7~8.
- Charged Device Model, JESD22-C101: 1.0 kV at Pins 1~8.

## Recommended Operating Conditions

The Recommended Operating Conditions table defines the conditions for actual device operation. Recommended operating conditions are specified to ensure optimal performance to the datasheet specifications. Fairchild does not recommend exceeding them or designing to Absolute Maximum Ratings.

| Symbol | Parameter                      | Min. | Max. | Unit |
|--------|--------------------------------|------|------|------|
| $T_J$  | Operating Junction Temperature | -40  | +125 | °C   |

## Electrical Characteristics

Unless otherwise noted,  $R_{CS} = 10\ \Omega$ , and  $T_A = 25^\circ\text{C}$ . Currents are defined as positive into the device and negative out of the device.

| Symbol                             | Parameter                      | Conditions                                              | Min. | Typ. | Max.  | Unit             |
|------------------------------------|--------------------------------|---------------------------------------------------------|------|------|-------|------------------|
| <b>VIN Supply</b>                  |                                |                                                         |      |      |       |                  |
| $I_{QIES,VIN}$                     | $V_{IN}$ Quiescent Current     | $V_{IN} = 500\ \text{V}$ Maximum                        |      | 0.75 | 1.20  | mA               |
| <b>VDD Output</b>                  |                                |                                                         |      |      |       |                  |
| $V_{DD}$                           | VDD Voltage                    | $V_{IN} = 20.0\ \text{V}$                               | 16   | 17   | 18    | V                |
| <b>LED Current</b>                 |                                |                                                         |      |      |       |                  |
| $I_{LED1}$                         | LED1 Current                   | $V_{IN} = 20.0\ \text{V}$ , $V_{LED1} = 20.0\ \text{V}$ | 17.4 | 23.0 | 28.6  | mA               |
| $I_{LED2}$                         | LED2 Current                   | $V_{IN} = 20.0\ \text{V}$ , $V_{LED2} = 20.0\ \text{V}$ | 40.4 | 47.0 | 53.6  | mA               |
| $I_{LED3}$                         | LED3 Current                   | $V_{IN} = 20.0\ \text{V}$ , $V_{LED3} = 35.0\ \text{V}$ | 78.2 | 86.0 | 93.8  | mA               |
| $I_{LED4}$                         | LED4 Current                   | $V_{IN} = 20.0\ \text{V}$ , $V_{LED4} = 20.0\ \text{V}$ | 87.8 | 96.0 | 104.2 | mA               |
| <b>Over-Temperature Protection</b> |                                |                                                         |      |      |       |                  |
| $T_{OTP}$                          | OTP Temperature <sup>(7)</sup> |                                                         |      | 170  |       | $^\circ\text{C}$ |
| <b>Leakage Current</b>             |                                |                                                         |      |      |       |                  |
| $I_{LED1-LK}$                      | LED1 Leakage Current           | $V_{LED1} = 500\ \text{V}$ , $V_{IN} = 0\ \text{V}$     |      |      | 1     | $\mu\text{A}$    |
| $I_{LED2-LK}$                      | LED2 Leakage Current           | $V_{LED2} = 500\ \text{V}$ , $V_{IN} = 0\ \text{V}$     |      |      | 1     | $\mu\text{A}$    |
| $I_{LED3-LK}$                      | LED3 Leakage Current           | $V_{LED3} = 500\ \text{V}$ , $V_{IN} = 0\ \text{V}$     |      |      | 1     | $\mu\text{A}$    |
| $I_{LED4-LK}$                      | LED4 Leakage Current           | $V_{LED4} = 200\ \text{V}$ , $V_{IN} = 0\ \text{V}$     |      |      | 1     | $\mu\text{A}$    |

### Notes:

- Not tested in production. Internal over-temperature protection circuitry protects the device from permanent damage. LEDs shut down at the junction temperature of  $T_J = 170^\circ\text{C}$  (typical.).

# Typical Performance Characteristics

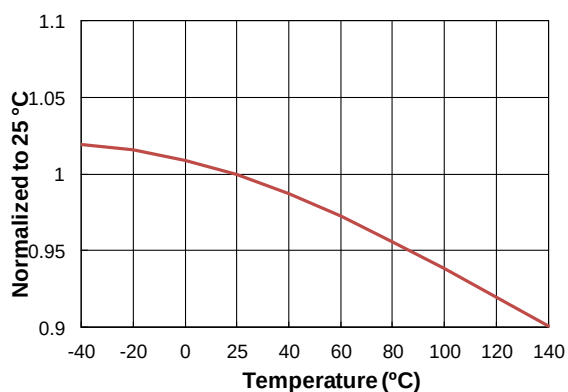


Figure 4.  $I_{Q_{UIES,VIN}}$  vs. Temperature

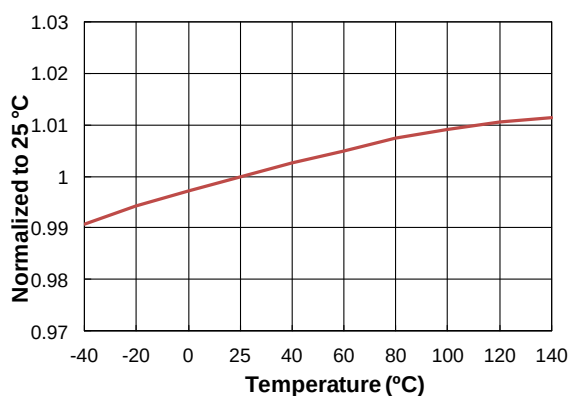


Figure 5.  $V_{DD}$  vs. Temperature

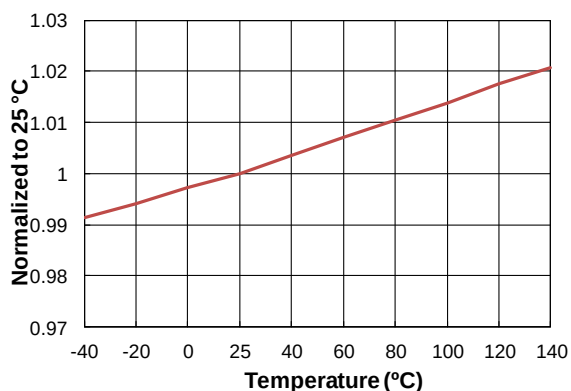


Figure 6.  $I_{LED1}$  vs. Temperature

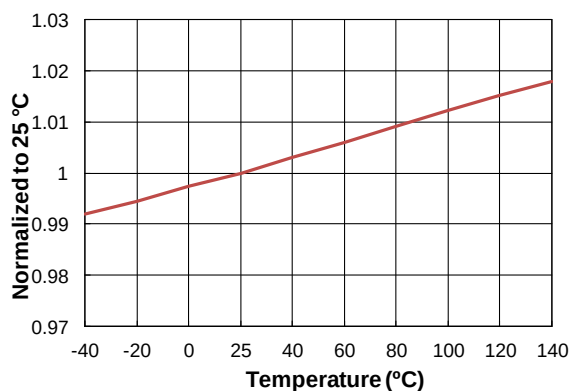


Figure 7.  $I_{LED2}$  vs. Temperature

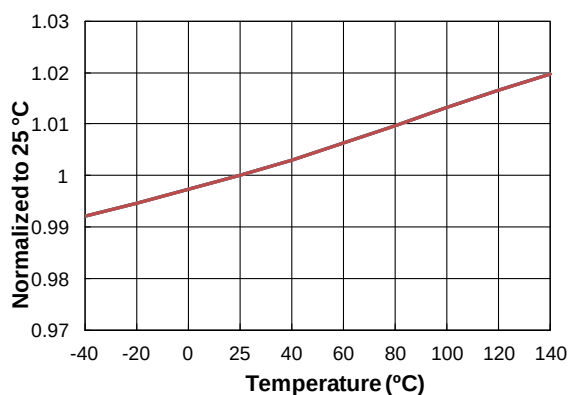


Figure 8.  $I_{LED3}$  vs. Temperature

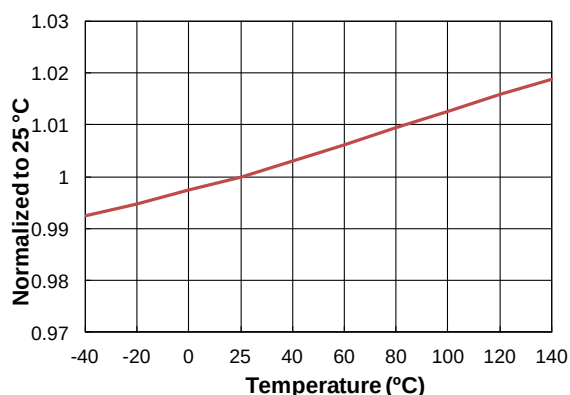


Figure 9.  $I_{LED4}$  vs. Temperature

## Functional Description

The FL77904 can drive LED strings attached directly to the rectified AC mains using only two external RC components ( $R_{CS}$  and  $C_{VDD}$ ). With 4 integrated high voltage current sink, LED current in each string is precisely controlled with system compactness. High PF and low THD are obtained by the optimized current sink levels. Phase-cut dimming is easily obtained with wide dimming range and good dimmer compatibility. Flicker index in the direct AC drive topology can be improved by adopting proprietary self valley-fill solution.

## Operation

When the rectified AC line voltage,  $V_{IN}$ , is higher than the forward voltage of the consecutive LED groups, each LED group turns on automatically as the corresponding current sink has enough voltage headroom across it. Each current sink increases up to the predefined current level and maintains the level until the following channel current sink gets enough voltage headroom across it.

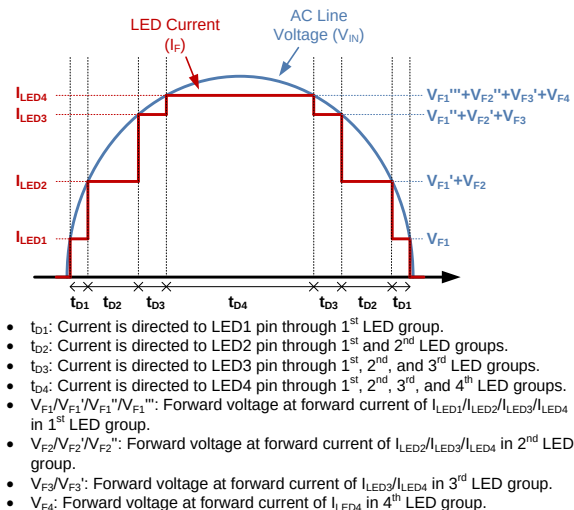


Figure 10. FL77904 Operation

When  $V_{IN}$  reaches the forward voltage across the 1st LED group ( $V_{F1}$ ) at forward current  $I_F = I_{LED1}$ , the current drawn from the  $V_{IN}$  is directed to the LED1 through the 1st LED group. In sequence, when  $V_{IN}$  reaches forward voltage across the 1st and 2nd LED groups ( $V_{F1}+V_{F2}$ ) at  $I_F = I_{LED2}$ , the current is directed to LED2 across the 1st and 2nd LED groups. Then, when  $V_{IN}$  reaches  $V_{F1}+V_{F2}+V_{F3}$  at  $I_F=I_{LED3}$ , the LED current go through 1st, 2nd, and 3rd LED groups and sinks to the LED3. Finally, when  $V_{IN}$  reaches  $V_{F1}+V_{F2}+V_{F3}+V_{F4}$  at  $I_F=I_{LED4}$ , the current goes through all 4 LED groups and is directed to the LED4.

Whenever the active channel (one that is sinking LED current) is changed from one channel to the adjacent channel with respect to the change in the  $V_{IN}$ , the new active channel's current increases gradually while the existing active channel's current decreases gradually. This smooth current transition reduces frequency

harmonic contents and improves power factor as well as Electromagnetic Interference (EMI) characteristics.

By fully utilizing available headroom, the FL77904 offers high efficiency, power factor and low harmonic distortion. Typically, power factor is higher than 0.98 and THD is lower than 20%. The efficiency heavily depends on a LED configuration.

## LED Current and Power Setting

The LED current is managed by an external current sense resistor  $R_{CS}$ . Regulation target of each channel's current sink is calculated as follows.

$$I_{LED1} = \frac{0.23}{R_{CS}}, I_{LED2} = \frac{0.47}{R_{CS}},$$

$$I_{LED3} = \frac{0.86}{R_{CS}}, \text{ and } I_{LED4} = \frac{0.96}{R_{CS}}. \quad (1)$$

Root-mean-square (RMS) value of the input current can be calculated using the peak regulated current,  $I_{LED4}$ , and crest factor. Since the LED current waveform is similar to the AC line voltage, the crest factor is close to the crest factor of a sine wave,  $\sqrt{2}=1.414$ . But the actual crest factor depends on the flattened time of the  $I_{LED4}$  and LED configuration. With FL77904, the typical crest factor is approximately 1.35. Thus, based on estimated input power,  $P_{IN}$ , the  $R_{CS}$  resistor value can be calculated as follows.

$$R_{CS} = \frac{0.96 \times V_{AC.RMS}}{1.35 \times P_{IN}} \quad (2)$$

The actual  $R_{CS}$  needs to be adjusted with respect to the LED configuration.

## LED Configuration

In the LED configuration, it is required to increase the total LED forward voltage to improve efficiency. For example, compared to using 4 LEDs with  $V_F$  of 60 V (total  $V_F = 60 \text{ V} \times 4 \text{ channels} = 240 \text{ V}$ ) for each LED group, using 4 LEDs with  $V_F$  equal to 65 V (total  $V_F = 65 \text{ V} \times 4 \text{ channels} = 260 \text{ V}$ ) will improve the efficiency simply due to the higher total  $V_F$ . Each LED channel can have different  $V_F$ . For example, if a design is implemented with 144 pieces of 3-V LEDs for replacement of 2-feet fluorescent lamp, designer can assign flexible numbers of LEDs for LED channels such as 25s2p-32s2p-6s2p-18s1p ("s" stands for LEDs in series and "p" stands for LEDs in parallel) or 18s2p-18s2p-18s2p-36s1p.

In any LED structure,  $V_F$  of first LED group should be higher than  $V_{IN}$ -pin turn-on voltage, which is 20 V. If the  $V_F$  of the first LED group is configured to be lower than  $V_{IN}$ -pin turn-on voltage,  $I_{LED1}$  will not have the correct regulation level when input voltage,  $V_{IN}$ , is just exceeds the  $V_F$ .



A good starting point for choosing a LED configuration is to have about 260 V~280 V of the total  $V_F$  for 220 V<sub>AC</sub> mains and 130 V~140 V of the total  $V_F$  for 120 V<sub>AC</sub>.

### Internal Shunt Regulator Output, $V_{DD}$

The system implemented with FL77904 does not require a bulk capacitor after bridge-rectification diodes. As a result, the  $V_{DD}$ , which supplies biasing voltage for the FL77904, has voltage ripple like the rectification voltage after the bridge diodes as shown in Figure 11.

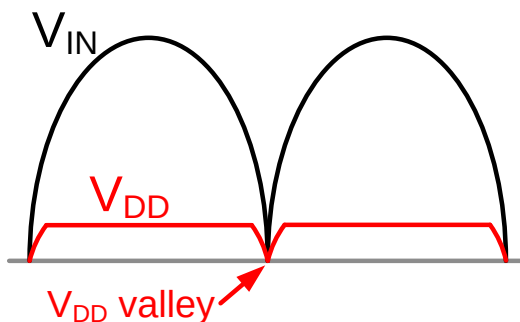
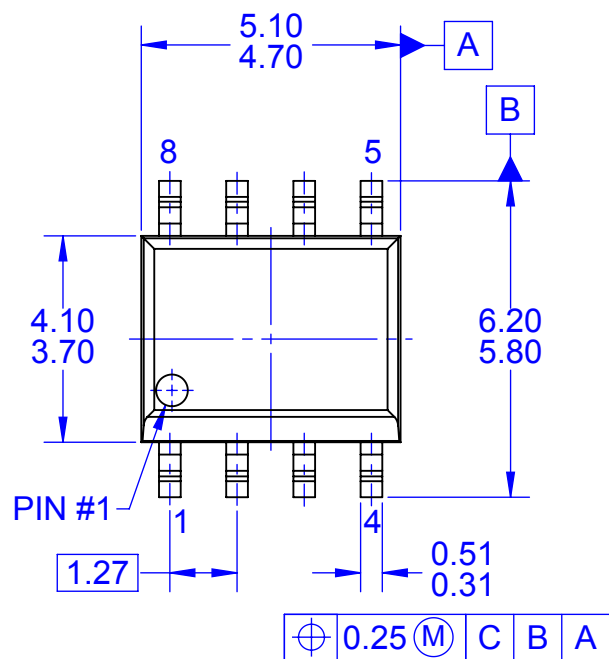


Figure 11.  $V_{DD}$  Ripple without  $C_{VDD}$

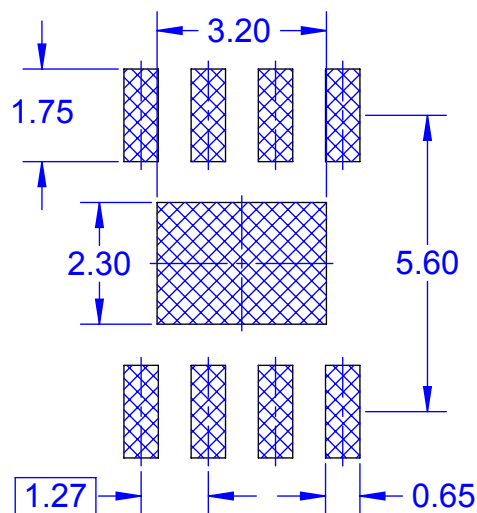
The  $V_{DD}$  ripple can be reduced by a bypassing capacitor,  $C_{VDD}$ . If the  $C_{VDD}$  is not used, or its value is small, the  $V_{DD}$  voltage fluctuates and goes even down to 0 V. It makes the FL77904 reset, but the FL77904 automatically restarts every cycle when the AC line voltage reaches a certain level. General design suggestion is to add  $C_{VDD}$  for noise filtering. The recommended  $C_{VDD}$  value is 1  $\mu$ F with 50 V of voltage rating.

### Over-Temperature Protection (OTP)

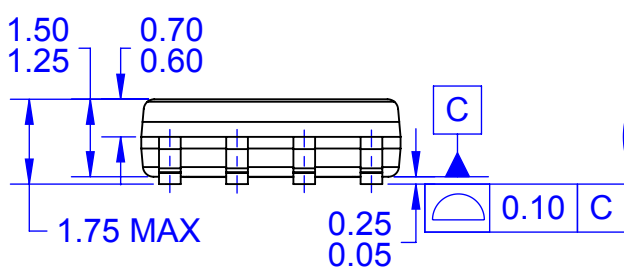
The FL77904 provides over temperature protection (OTP) inherently. When the driver's junction temperature exceeds a specified threshold temperature ( $T_J = 170^\circ\text{C}$ ), the driver will shut down automatically and recover once the temperature drops lower enough than the internal threshold temperature. Without this protection, the lifetime of the FL77904 can be reduced and irreparable damage can occur. Good thermal management is required to achieve best performance and long life span of the FL77904.



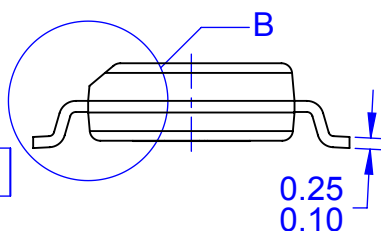
TOP VIEW



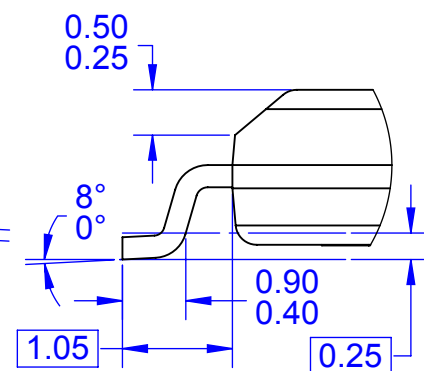
LAND PATTERN RECOMMENDATION



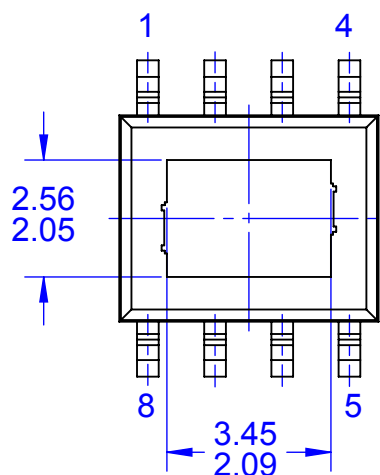
FRONT VIEW



SIDE VIEW



DETAIL B  
SCALE 2:1



BOTTOM VIEW

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